



US00D388066S

**United States Patent** [19]  
**Ishihara**

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[45] **Date of Patent: \*\*Dec. 23, 1997**

[54] **IC MODULE**

D. 368,903 4/1996 Ohmori et al. .... D14/117  
D. 369,156 4/1996 Ohmori et al. .... D14/117  
D. 369,157 4/1996 Ohmori et al. .... D14/117

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[\*\*] **Term: 14 Years**

[21] **Appl. No.: 62,837**

[22] **Filed: Nov. 27, 1996**

[57] **CLAIM**

The ornamental design for an IC module, as shown and described.

[30] **Foreign Application Priority Data**

**DESCRIPTION**

May 29, 1996 [JP] Japan ..... 8-15401

[51] **LOC (6) Cl. .... 14-02**

[52] **U.S. Cl. .... D14/114; D14/117**

[58] **Field of Search .... D14/114, 117, D14/107; 235/378-380, 492, 487; 257/731, 669**

FIG. 1 is a front, bottom and right side perspective view of an IC module showing my new design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a right side elevational view thereof, the opposite side being a mirror image;  
FIG. 4 is a top plan view thereof;  
FIG. 5 is a bottom plan view thereof; and,  
FIG. 6 is a rear elevational view thereof.

[56] **References Cited**

**U.S. PATENT DOCUMENTS**

D. 357,909 5/1995 Gloton ..... D14/114

**1 Claim, 1 Drawing Sheet**

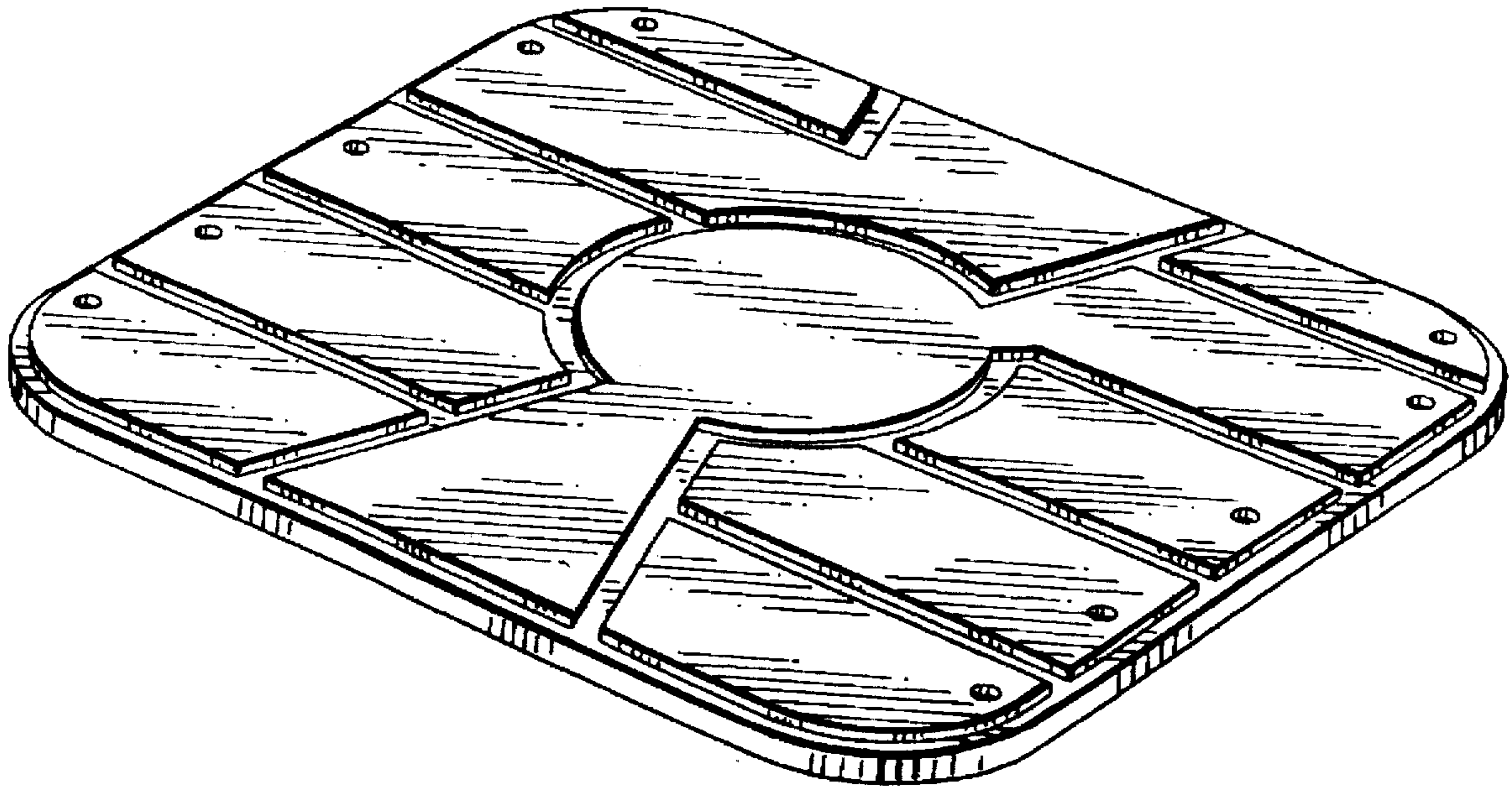


FIG. 1

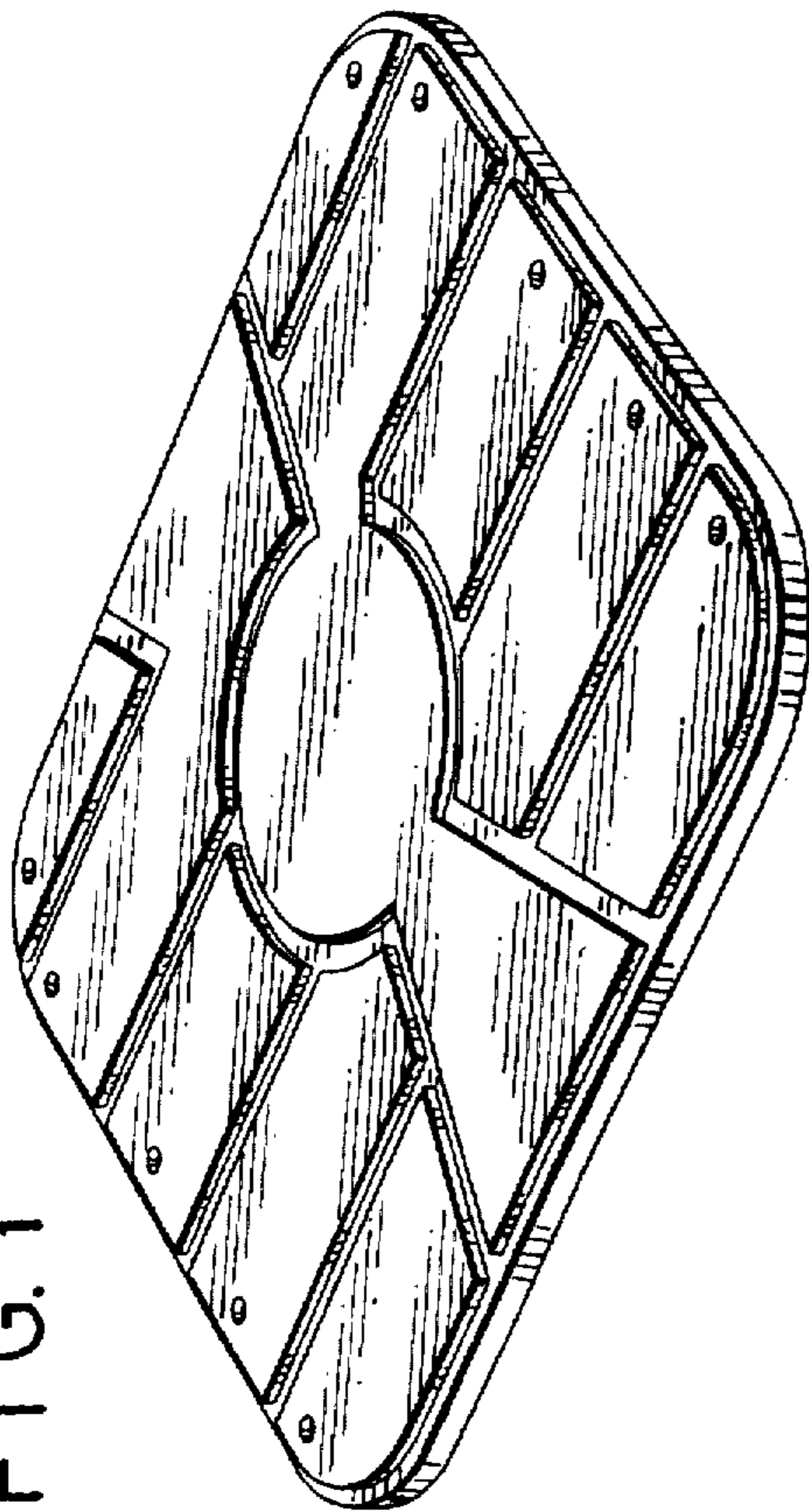


FIG. 2

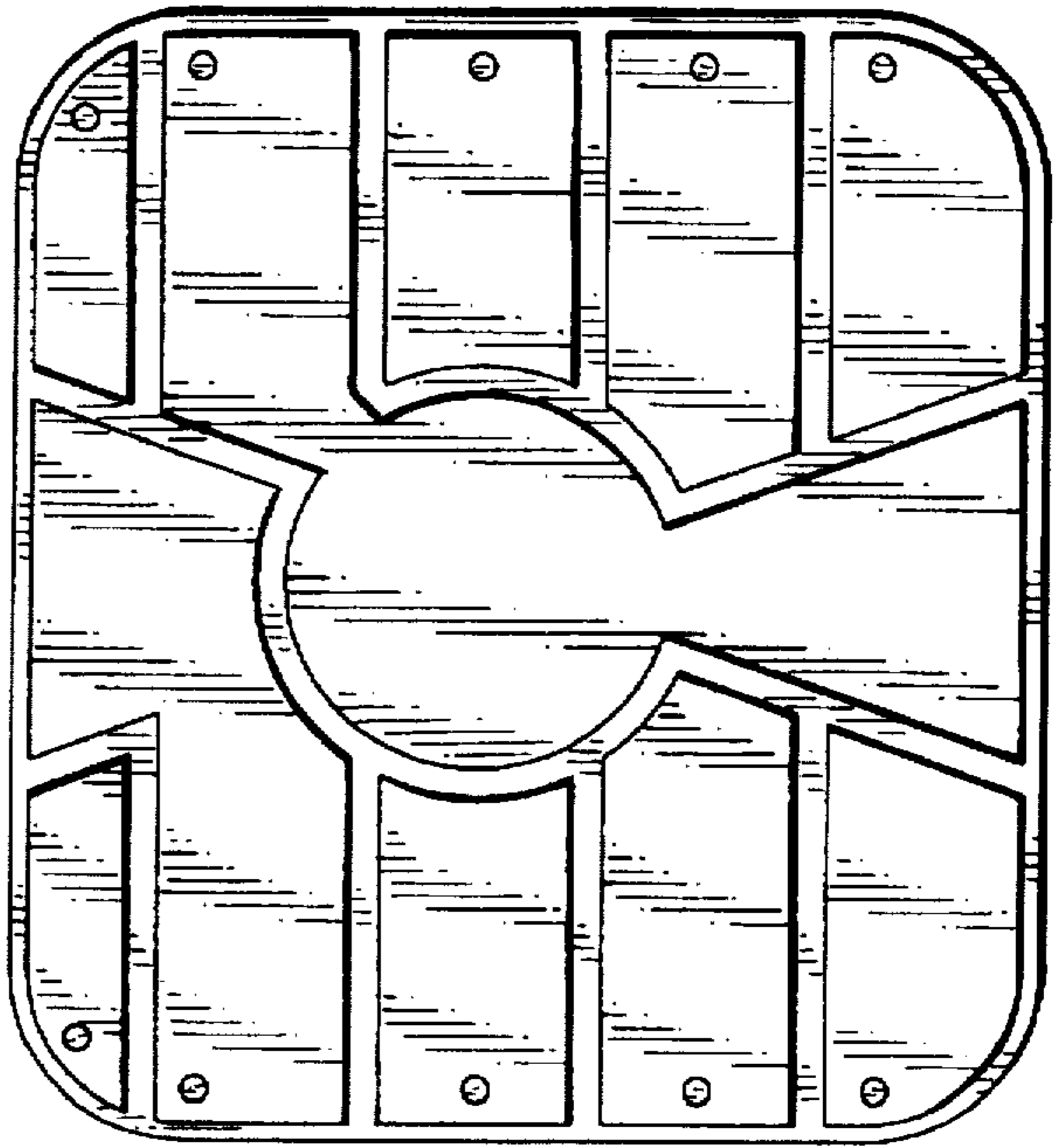


FIG. 3

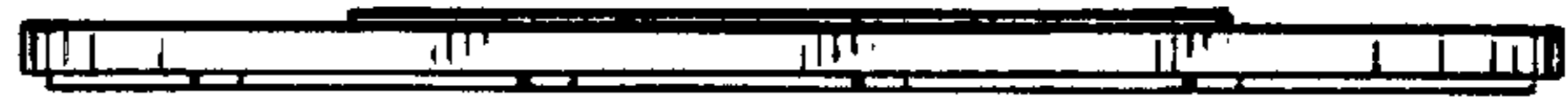


FIG. 4

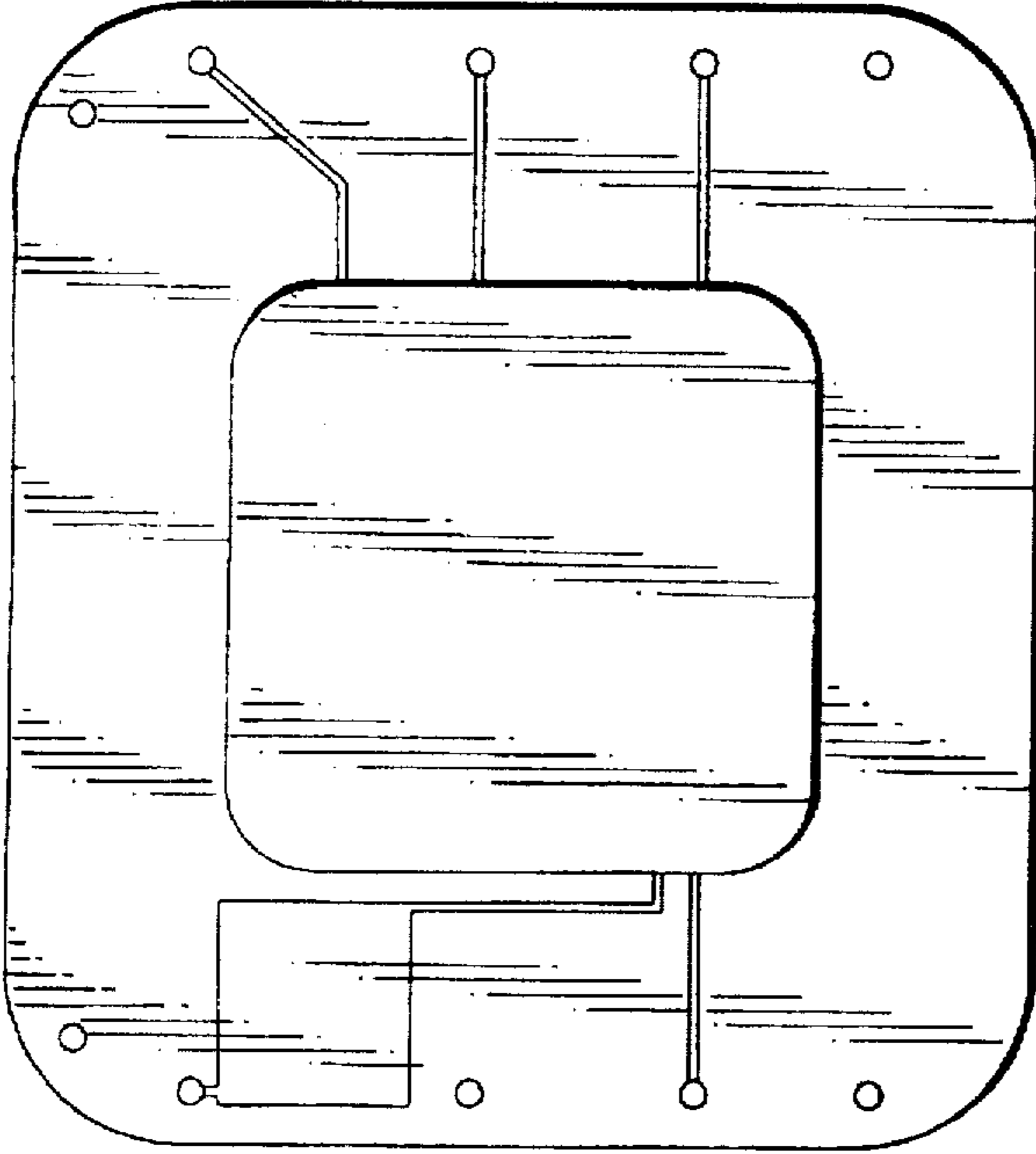


FIG. 5



FIG. 6

